



100% Material Declaration Data Sheet CPG132

PK101 (v1.3) September 28, 2006

Material Declaration Data Sheet

Average Weight: 0.1 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.00203	2.03%
	Silicon	7440-21-3	100.00		0.00203	
Die Attach Material					0.00038	0.38%
	Silver	7440-22-4	78.00		0.0002964	
	Resin (EP)	Trade Secret	22.00		0.0000836	
Encapsulant					0.03444	34.44%
	Epoxy Resins	Trade Secret	6.00		0.0020664	
	Phenolic Resins	Trade Secret	6.00		0.0020664	
	Carbon Black	1333-86-4	0.50		0.0001722	
	Silica	60676-86-0	84.00		0.0289296	
	Bismuth	7440-69-9	Max 1.00		0.0003444	
	Metal Hydroxide	Trade Secret	2.50		0.000861	
Laminate					0.01085	10.85%
	Bismaleimide/Triazine Board	13676-54-5 / 25722-66-1	72.685		0.0078863225	
	Copper	7440-50-8	9.880		0.00107198	
	Nickel	7440-02-0	7.270		0.000788795	
	Gold	7440-57-5	1.160		0.00012586	
	Antimony Pentoxide	1314-60-9	0.005	Flame Retardant	0.0000005425	
	Brominated Resin	68541-56-0	9.000	Flame Retardant	0.0009765	
Bond Wire					0.00022	0.22%
	Gold	7440-57-5	100.00		0.00022	
Solder Balls					0.05208	52.08%
	Tin	7440-31-5	95.50		0.0497364	
	Silver	7440-22-4	4.00		0.0020832	
	Copper	7440-50-8	0.50		0.0002604	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/20/06	1.0	Initial release.
6/01/06	1.1	100% Material Declaration.
8/07/06	1.2	Corrected Laminate substance % and weight for Antimony Pentoxide.
9/28/06	1.3	Updated component descriptions.